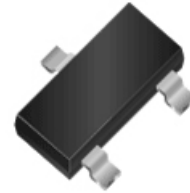


## WNM2027

N-Channel, 20V, 3.6A, Power MOSFET

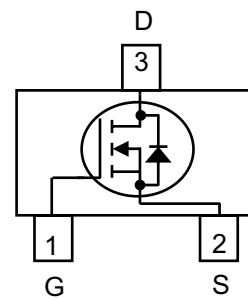
$V_{(BR)DSS}$	<b>Rds(on)</b> <b>(Max. mΩ)</b>	<b>Id</b> <b>(A)</b>
20	45 @ 4.5V	3.6
	55 @ 2.5V	3.1
	66 @ 1.8V	1.5



SOT-23

### Descriptions

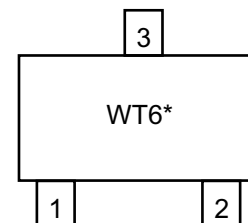
The WNM2027 is N-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. This device is suitable for use in DC-DC conversion and power switch applications. Standard Product WNM2027 is Pb-free.



Configuration (Top View)

### Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance for higher DC current
- Extremely Low Threshold Voltage
- Small package SOT-23



WT6 = Device Code  
\* = Month (A~Z)

### Marking

### Applications

- Driver for Relay, Solenoid, Motor, LED etc.
- DC-DC converter circuit
- Power Switch
- Load Switch

### Order Information

Device	Package	Shipping
WNM2027-3/TR	SOT-23	3000/Tape&Reel

**WNM2027**

<b>ABSOLUTE MAXIMUM RATINGS</b> $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted					
Parameter		Symbol	10 S	Steady State	Unit
Drain-Source Voltage		$V_{DS}$	20		V
Gate-Source Voltage		$V_{GS}$	$\pm 8$		
Continuous Drain Current ( $T_J = 150\text{ }^\circ\text{C}$ ) <sup>a</sup>	$T_A = 25\text{ }^\circ\text{C}$	$I_D$	3.2	2.9	A
	$T_A = 70\text{ }^\circ\text{C}$		2.5	2.3	
Maximum Power Dissipation <sup>a</sup>	$T_A = 25\text{ }^\circ\text{C}$	$P_D$	0.8	0.7	W
	$T_A = 70\text{ }^\circ\text{C}$		0.5	0.4	
Continuous Drain Current ( $T_J = 150\text{ }^\circ\text{C}$ ) <sup>b</sup>	$T_A = 25\text{ }^\circ\text{C}$	$I_D$	2.9	2.7	A
	$T_A = 70\text{ }^\circ\text{C}$		2.3	2.1	
Maximum Power Dissipation <sup>b</sup>	$T_A = 25\text{ }^\circ\text{C}$	$P_D$	0.6	0.5	W
	$T_A = 70\text{ }^\circ\text{C}$		0.4	0.3	
Pulsed Drain Current <sup>c</sup>		$I_{DM}$	10		A
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	-55 to 150		$^\circ\text{C}$

<b>THERMAL RESISTANCE RATINGS</b>					
Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance <sup>a</sup>	$t \leq 10\text{ s}$	$R_{\theta JA}$	125	150	$^\circ\text{C}/\text{W}$
	Steady State		140	175	
Junction-to-Ambient Thermal Resistance <sup>b</sup>	$t \leq 10\text{ s}$	$R_{\theta JA}$	150	180	
	Steady State		165	210	
Junction-to-Case Thermal Resistance		$R_{\theta JC}$	60	76	

- a Surface mounted on FR4 Board using 1 in sq pad size, 1oz Cu.
- b Surface mounted on FR4 board using the minimum recommended pad size, 1oz Cu.
- c Repetitive rating, pulse width limited by junction temperature,  $t_p = 10\mu\text{s}$ , Duty Cycle=1%
- d Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})} = 150\text{ }^\circ\text{C}$ .

**WNM2027**
**Electronics Characteristics**

(Ta=25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\mu\text{A}$	20			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 16\text{ V}, V_{GS} = 0\text{ V}$			0.5	$\mu\text{A}$
Gate-to-source Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 8.0\text{ V}$			$\pm 100$	nA
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	0.4	0.6	1	V
Drain-to-source On-resistance	$R_{DS(on)}$	$V_{GS} = 4.5\text{ V}, I_D = 3.6\text{ A}$		40	45	m $\Omega$
		$V_{GS} = 2.5\text{ V}, I_D = 3.1\text{ A}$		47	55	
		$V_{GS} = 1.8\text{ V}, I_D = 1.5\text{ A}$		55	66	
		$V_{GS} = 1.5\text{ V}, I_D = 1.0\text{ A}$		65	75	
Forward Transconductance	$g_{FS}$	$V_{DS} = 5\text{ V}, I_D = 3.1\text{ A}$		11		S
<b>CHARGES, CAPACITANCES AND GATE RESISTANCE</b>						
Input Capacitance	$C_{ISS}$	$V_{GS} = 0\text{ V}, f = 1.0\text{ MHz},$ $V_{DS} = 10\text{ V}$		500	700	pF
Output Capacitance	$C_{OSS}$			68	150	
Reverse Transfer Capacitance	$C_{RSS}$			60	90	
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 4.5\text{ V}, V_{DS} = 10\text{ V},$ $I_D = 2.7\text{ A}$		6.5		nC
Threshold Gate Charge	$Q_{G(TH)}$			0.6		
Gate-to-Source Charge	$Q_{GS}$			0.8		
Gate-to-Drain Charge	$Q_{GD}$			1.5		
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	$t_d(ON)$	$V_{GS} = 4.5\text{ V}, V_{DS} = 10\text{ V},$ $R_L = 3\ \Omega, R_G = 6\ \Omega$		5	8	ns
Rise Time	$t_r$			6	9	
Turn-Off Delay Time	$t_d(OFF)$			30	45	
Fall Time	$t_f$			8	12	
<b>DRAIN-SOURCE DIODE CHARACTERISTICS</b>						
Forward Recovery Voltage	$V_{SD}$	$V_{GS} = 0\text{ V}, I_S = 1.0\text{ A}$	0.5	0.62	0.9	V